

AMENDMENTS

IN THE CLAIMS

Claims 1-280. (canceled)

281. (previously added) A method for fabricating an electronic component, comprising:
joining a die and a substrate, wherein said die has a top surface at a horizontal level; and
after said joining said die and said substrate, depositing a bump over said horizontal level,
wherein said bump comprises gold.

282. (currently amended) A method for fabricating an electronic component, comprising:
providing a die having a top surface at a horizontal level;
depositing an insulating insulation layer over a die said horizontal level, wherein said
insulating insulation layer comprises a porous structure, and
~~depositing a metal layer over said horizontal level.~~

283. (currently amended) A method for fabricating an electronic component, comprising:
~~providing joining a die and a substrate, wherein said die has having a top surface at a~~
horizontal level; and
~~depositing a metal layer over said top surface and extending to a place not over said die;~~
and

after said joining said die and said substrate, depositing a passive device over said
horizontal level.

284. (previously added) A method for fabricating an electronic component, comprising:
providing a die having a top surface at a horizontal level; and
depositing a waveguide over said horizontal level.

285. (previously added) A method for fabricating an electronic component, comprising:
providing a die having a top surface at a horizontal level; and
depositing a micro electronic mechanical sensor (MEMS) over said horizontal level.

286. (currently amended) A method for fabricating an electronic component, comprising:
providing a substrate comprising an organic material;
~~joining multiple dies with said substrate;~~
depositing an insulating layer over a circuitry element;
grinding said insulating layer; and
depositing a metal layer over said insulating layer. ~~multiple dies, wherein said depositing~~
~~said metal layer comprises electroplating; and~~
~~cutting said substrate.~~